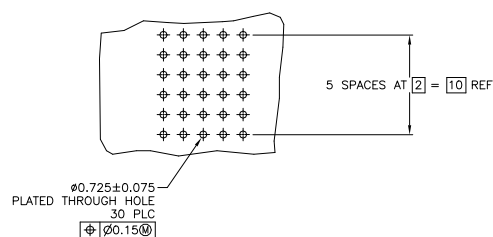
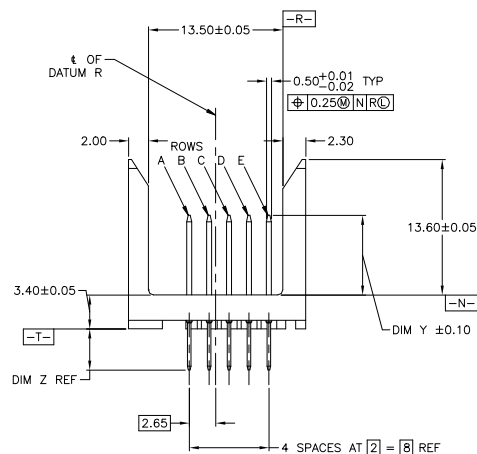
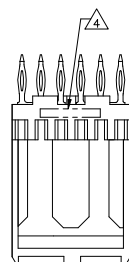
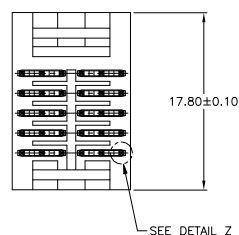
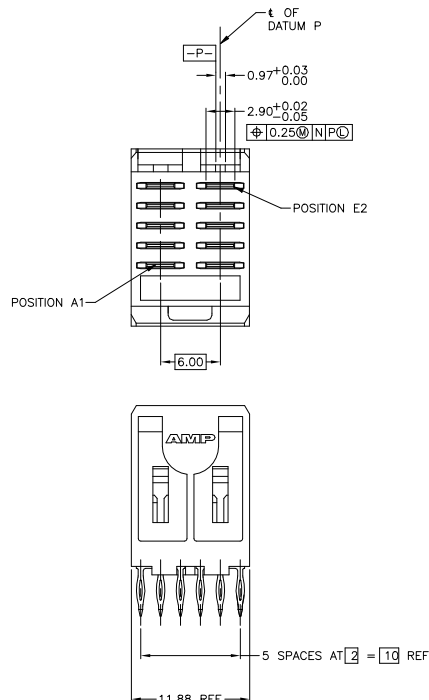
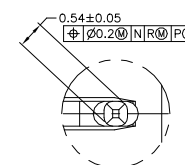


REVISIONS				
REV	DATE	DESCRIPTION	BY	APP
A3	24SEP2020	REVISED PER ECO-20-013368	RZ	HL



RECOMMENDED CIRCUIT PATTERN
PER IPC-D300 TYPE II, CLASS C
(COMPONENT SIDE)

- 1 HOUSING MATERIAL: LIQUID CRYSTAL POLYMER, NATURAL.
- 2 CONTACT MATERIAL: COPPER ALLOY.
- 3 CONTACT FINISH:
UNDERPLATE (ENTIRE CONTACT):
0.00127 MIN NICKEL PER SAE-AMS-QQ-N-290
ON MATING SURFACES:
FLASH GOLD PER ASTM B 488, OVER
0.00076 MIN PALLADIUM-NICKEL OVER UNDERPLATE, OR
0.00076 MIN GOLD PER ASTM B 488 OVER UNDERPLATE.
ON LEADS:
0.00127 MIN MATTE TIN PER ASTM B 545 OVER UNDERPLATE.
LUBRICATION (MIN MATING SURFACES):
SURFACE CONDITIONER AFTER PLATING.
- 4 PART NUMBER AND DATE CODE IN APPROXIMATE AREA AS SHOWN.



DETAIL Z
SCALE 20:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV	1-7-98	TE Connectivity Ltd.	
DESIGNER: T. SHUEY		CHK	1-16-98	NAME	
DRAWN: W. MILLHICES		APP	1-16-98	ASSEMBLY, PIN, VERTICAL,	
PRODUCT SPEC: 108-1441		SIZE		5 ROW, POWER MODULE, PRESS FIT	
APPLICATION SPEC: 114-1075		SCALE		LEAD, Z-PACK 2mm HM	
MATERIAL		DATE CODE		RESTRICTED TO	
FINISH		DRAWING NO		A1 00779	
WEIGHT		C=5536642		REV	
CUSTOMER DRAWING		SCALE		4:1	
		SHEET		1 OF 2	
				REV A3	

